E7515A-01A

Modification Recommended Service Note

Supersedes:
E7515A-01

E7515A UXM Wireless Test Set

Serial Numbers: TH53460050 / TH55345133
MY54450102 / MY55210227

Modify The Embedded PC To Improve Boot Reliability

Parts Required:

P/N	Description	Qty.

NONE

ADMINISTRATIVE INFORMATION

ACTION CATEGORY:	[[]] ON SPECIFIED FAILURE [X] AGREEABLE TIME	STANDARDS LABOR: 1.0 Hours			
LOCATION CATEGORY:	[[]] CUSTOMER INSTALLABLE [[]] ON-SITE (active On-site contract required) [X] SERVICE CENTER [[]] CHANNEL PARTNERS	SERVICE INVENTORY:	[[]] RETURN [[]] SCRAP [X] SEE TEXT	USED PARTS:	[[]] RETURN [[]] SCRAP [X] SEE TEXT
AVAILABILITY:	PRODUCT’S SUPPORT LIFE	NO CHARGE AVAILABLE UNTIL: (date required - 1 yr. min.)			
	[[]] Calibration Required [X] Calibration NOT Required	PRODUCT LINE: 13 AUTHOR: FC			

ADDITIONAL INFORMATION:

This modification does not impact service inventory.
This modification does not require the removal or disposal of any parts.

Situation:

The E7515A will fail to boot if either of the RAM modules on the Embedded PC is not fully engaged in the memory slot.

A design change to prevent this from happening was implemented on every instrument from serial number TH54250357 onwards.

This design change was later revised to further improve reliability, and is implemented on every instrument from serial number MY55210228 onwards.

Solution/Action:

Remove the outer covers from the instrument and inspect the RAM modules on the Embedded PC. If the RAM modules have been secured with thermal glue (as shown in Figure 1), then this service note does not apply – the modification has already been implemented.

Take note that the glue must be applied along the full length of all 4 latches, securing them to the RAM sockets (as shown in the right-side of Figure 1). This is the revised design change that further improves reliability.

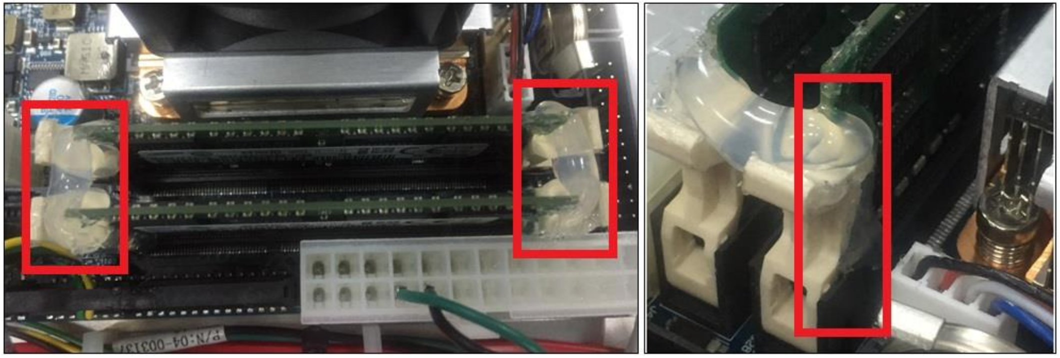

Figure 1

If the RAM modules have not been secured with glue, or if the glue is present but does not secure the latches to the RAM sockets, then ensure they are both fully engaged and locked in their memory slots (as shown in Figure 2).

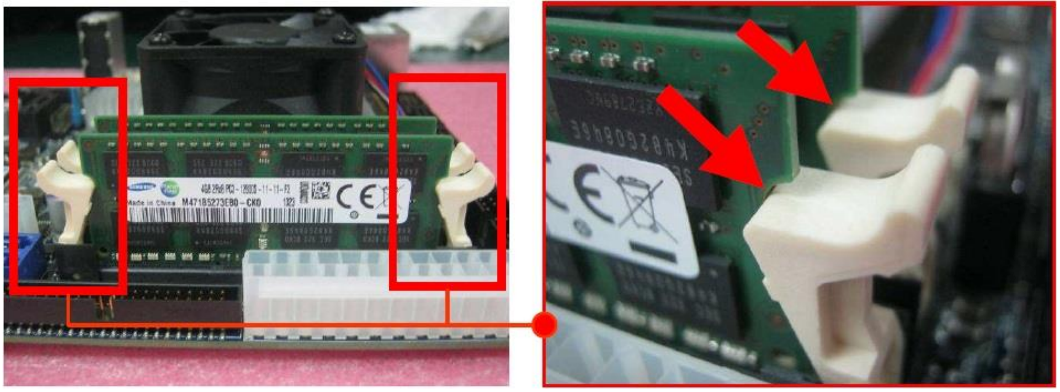

Figure 2

Carefully apply thermal glue as indicated in Figure 1. Wait for the glue to harden before re-assembling the instrument.

The following thermal glue is recommended, but similar alternatives can also be used:

Description	:	Power Adhesives Transparent 12mm Hot Melt Glue Stick
Mfr. Part No.	:	232-12-200-CRP-CP08-RS

Revision History:

Date	Service Note Revision	Author	Reason for Change
11 Feb 2015	01	Frank Corry	As Published
23 Sept 2015	02	Frank Corry	Revised to further improve reliability. Expanded the serial number range. Re-issued as E7515A-01A.